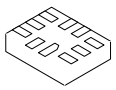

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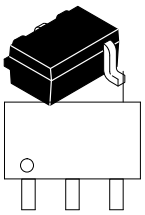
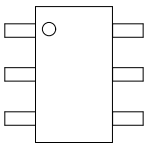
MU SUFFIX





Features

Typical Applications

ORDERING INFORMATION

[redacted]

Table 1. MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
	– –	–	–	
	–		–	
			–	
			–	
			±	
				°
			–	°
			±	
			±	
–			±	

Table 4. ELECTRICAL CHARACTERISTICS ° – _

Boldface _ ° °

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
INPUT						
	–		**−0.3**		**26**	

TYPICAL CHARACTERISTICS

Figure 2. Input Offset Voltage Production Distribution

Figure 3. Input Offset Voltage vs. Temperature

Figure 4. Common−Mode Rejection Production Distribution

Figure 5. Common−Mode Rejection Ratio vs. Temperature

Figure 6. Gain Error Production Distribution

Figure 7. Gain Error vs. Temperature

TYPICAL CHARACTERISTICS

TYPICAL CHARACTERISTICS

Basic Connections

Current Sensing Techniques

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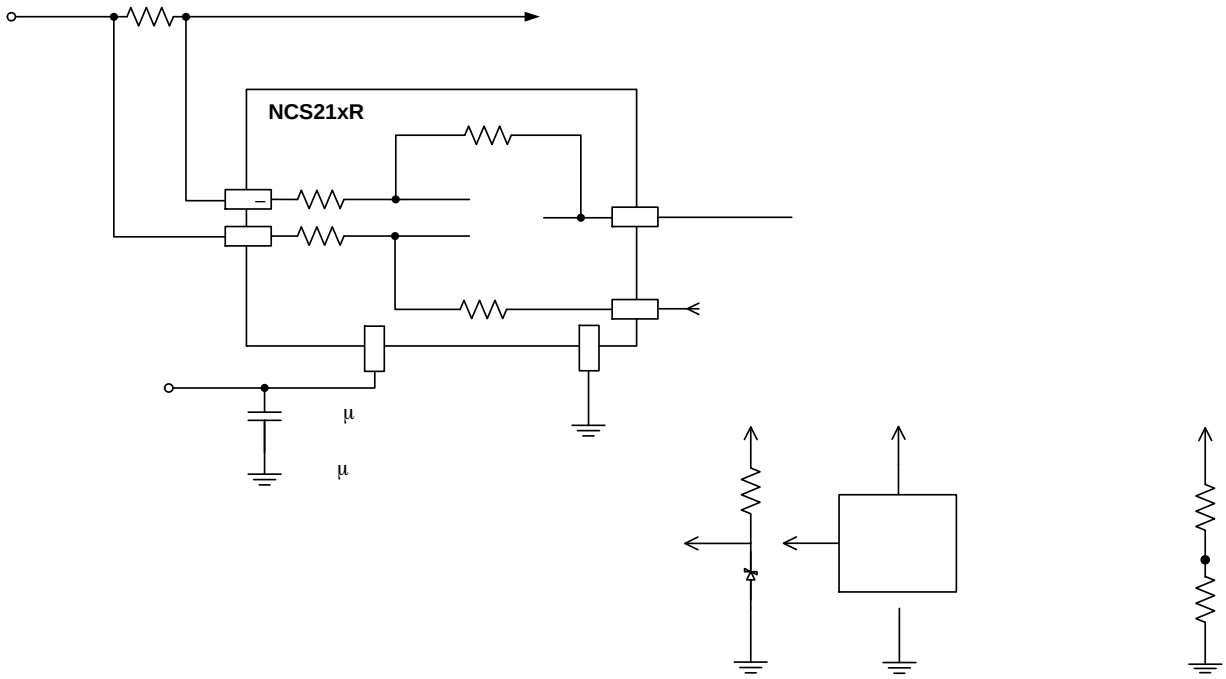
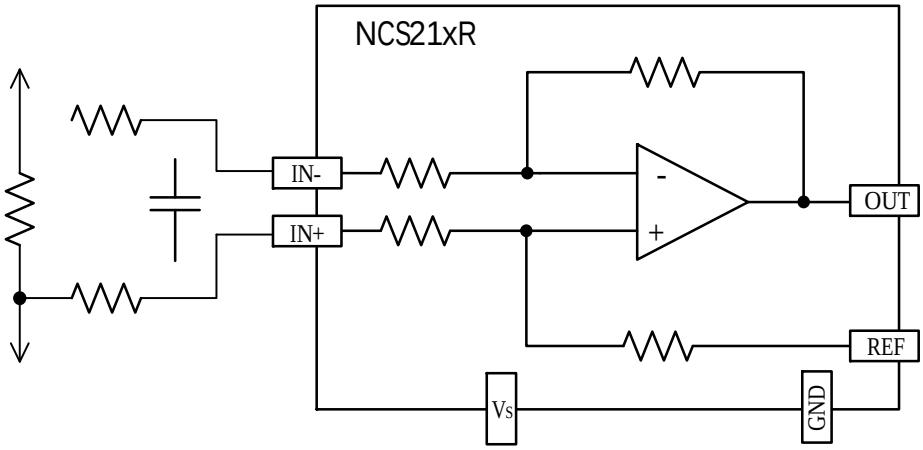

NCS21xR
μ
μ



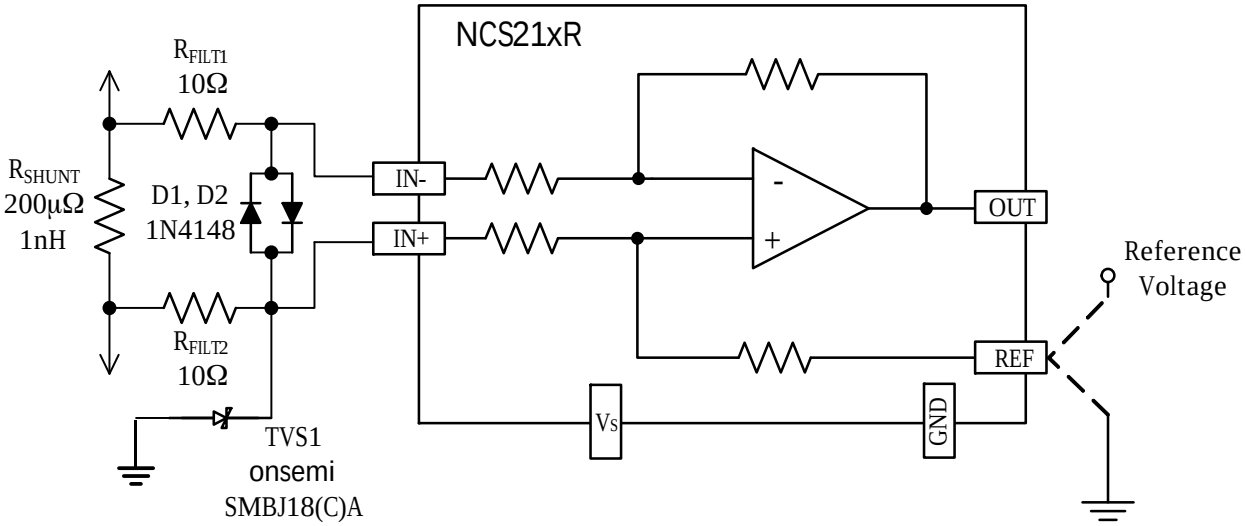


Figure 34. Single TVS transient common−mode protection

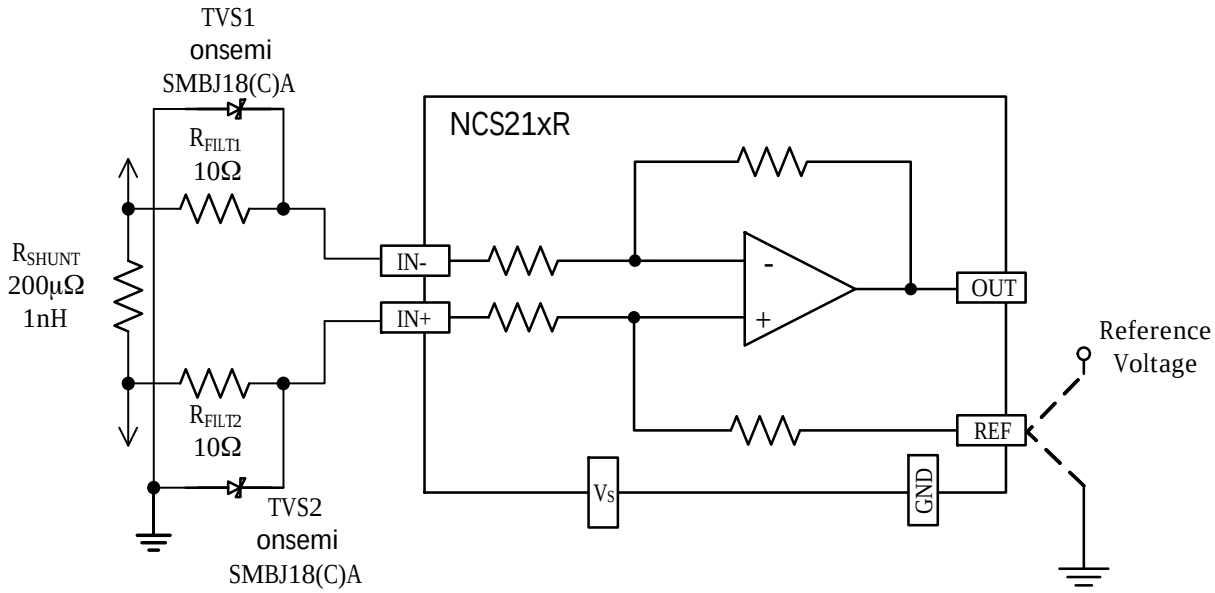


Figure 35. Dual TVS Transient Common−mode Protection

Selecting the Shunt Resistor

Kelvin Sensing

–

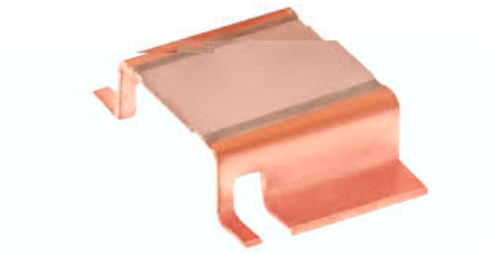
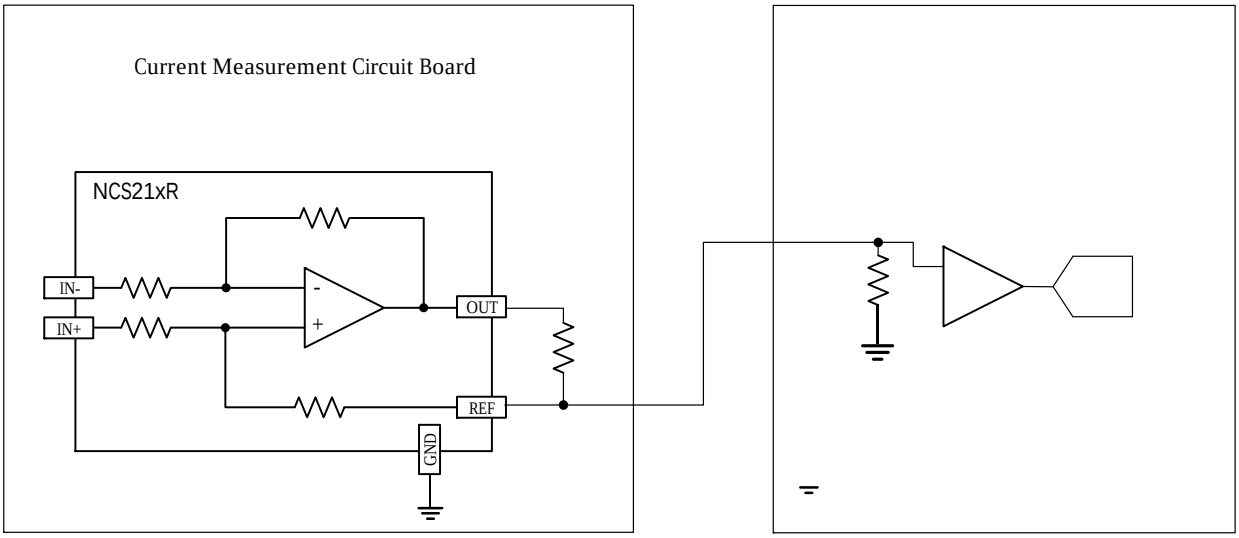


Figure 36. Surface Mount Kelvin Shunt

Current Output Configuration

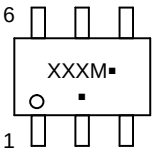


SC−88 2.00x1.25x0.90, 0.65P
CASE 419B−02
ISSUE Z

DATE 18 APR 2024

_ BURRS. MOLD FLASH,
PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.

GENERIC
MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING

STYLES ON PAGE 2

STYLE 1:
PIN 1. EMITTER 2
2. BASE 2
3. COLLECTOR 1
4. EMITTER 1
5. BASE 1
6. COLLECTOR 2

STYLE 2:
CANCELLED

STYLE 3:
CANCELLED

UQFN10 1.4x1.8, 0.4P
CASE 488AT
ISSUE A

DATE 01 AUG 2007